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### (54) PRINTED CIRCUIT BOARD HOUSING AND ASSEMBLY PROCESS

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#### (57)ABSTRACT

A housing for a printed circuit board (PCB) includes a housing base and a housing body. The housing base and the housing body each include first and second corresponding coupling members configured to provide a two-part coupling of the housing base to the housing body to form the housing. The housing base includes a PCB retainer. The housing body includes a corresponding PCB receiver. The PCB retainer and the PCB receiver are configured such that, when the housing base is coupled to the housing body, the PCB is retained in position securely therebetween.

